

BGY585A

550 MHz, 18.2 dB gain push-pull amplifier

Rev. 6 — 29 September 2010

Product data sheet

1. Product profile

1.1 General description

Hybrid amplifier module for CATV systems operating over a frequency range of 40 MHz to 550 MHz at a voltage supply of 24 V (DC). Intended for use as a final amplifier.

1.2 Features and benefits

- Excellent linearity
- Extremely low noise
- Silicon nitride passivation
- Rugged construction
- Optimal reliability ensured by TiPtAu metallized crystals

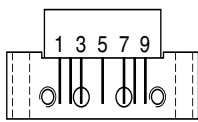
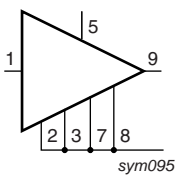
1.3 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G_p	power gain	$f = 50 \text{ MHz}$	17.7	-	18.7	dB
		$f = 550 \text{ MHz}$	18.8	-	20	dB
I_{tot}	total current consumption (DC)	$V_B = 24 \text{ V}$	-	220	240	mA

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	input		 <small>sym095</small>
2	common		
3	common		
5	+V _B		
7	common		
8	common		
9	output		



3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BGY585A	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads	SOT115J

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_i	RF input voltage		-	65	dBmV
T_{stg}	storage temperature		-40	+100	°C
T_{case}	case operating temperature		-20	+100	°C

5. Characteristics

Table 5. Characteristics

$T_{case} = 30\text{ °C}$; $Z_S = Z_L = 75\ \Omega$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Bandwidth 40 MHz to 550 MHz						
G_p	power gain	$f = 50\text{ MHz}$	17.7	-	18.7	dB
		$f = 550\text{ MHz}$	18.8	-	20	dB
SL	slope cable equivalent	$f = 40\text{ MHz to }550\text{ MHz}$	0.5	-	2	dB
FL	flatness of frequency response	$f = 40\text{ MHz to }550\text{ MHz}$	-	-	±0.2	dB
S_{11}	input return losses	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB
		$f = 160\text{ MHz to }550\text{ MHz}$	18	-	-	dB
S_{22}	output return losses	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB
		$f = 160\text{ MHz to }550\text{ MHz}$	18	-	-	dB
CTB	composite triple beat	77 channels flat; $V_o = 44\text{ dBmV}$; measured at 547.25 MHz	-	-	-59	dB
X_{mod}	cross modulation	77 channels flat; $V_o = 44\text{ dBmV}$; measured at 55.25 MHz	-	-	-62	dB
CSO	composite second order distortion	77 channels flat; $V_o = 44\text{ dBmV}$; measured at 548.5 MHz	-	-	-59	dB
d_2	second order distortion		[1] -	-	-72	dB
V_o	output voltage	$d_{im} = -60\text{ dB}$	[2] 61.5	-	-	dBmV
F	noise figure	$f = 550\text{ MHz}$	-	-	8	dB
I_{tot}	total current consumption (DC)	$V_B = 24\text{ V}$	[3] -	220	240	mA

Table 5. Characteristics ...continued

 $T_{case} = 30\text{ }^{\circ}\text{C}$; $Z_S = Z_L = 75\ \Omega$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
Bandwidth 40 MHz to 450 MHz							
G_p	power gain	$f = 50\text{ MHz}$	17.7	-	18.7	dB	
		$f = 450\text{ MHz}$	18.6	-	19.8	dB	
SL	slope cable equivalent	$f = 40\text{ MHz to }450\text{ MHz}$	0.5	-	1.8	dB	
FL	flatness of frequency response	$f = 40\text{ MHz to }450\text{ MHz}$	-	-	± 0.2	dB	
S_{11}	input return losses	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB	
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB	
		$f = 160\text{ MHz to }450\text{ MHz}$	18	-	-	dB	
S_{22}	output return losses	$f = 40\text{ MHz to }80\text{ MHz}$	20	-	-	dB	
		$f = 80\text{ MHz to }160\text{ MHz}$	19	-	-	dB	
		$f = 160\text{ MHz to }450\text{ MHz}$	18	-	-	dB	
CTB	composite triple beat	60 channels flat; $V_o = 46\text{ dBmV}$; measured at 445.25 MHz	-	-	-61	dB	
X_{mod}	cross modulation	60 channels flat; $V_o = 46\text{ dBmV}$; measured at 55.25 MHz	-	-	-61	dB	
CSO	composite second order distortion	60 channels flat; $V_o = 46\text{ dBmV}$; measured at 446.5 MHz	-	-	-61	dB	
d_2	second order distortion		[4]	-	-75	dB	
V_o	output voltage	$d_{im} = -60\text{ dB}$	[5]	64	-	dBmV	
F	noise figure	$f = 450\text{ MHz}$	-	-	7	dB	
I_{tot}	total current consumption (DC)	$V_B = 24\text{ V}$	[3]	-	220	240	mA

[1] $f_p = 55.25\text{ MHz}$; $V_p = 44\text{ dBmV}$; $f_q = 493.25\text{ MHz}$; $V_q = 44\text{ dBmV}$; measured at $f_p + f_q = 548.5\text{ MHz}$.

[2] Measured according to DIN45004B; $f_p = 540.25\text{ MHz}$; $V_p = V_o$; $f_q = 547.25\text{ MHz}$; $V_q = V_o - 6\text{ dB}$; $f_r = 549.25\text{ MHz}$; $V_r = V_o - 6\text{ dB}$; measured at $f_p + f_q - f_r = 538.25\text{ MHz}$.

[3] The module normally operates at $V_B = 24\text{ V}$, but is able to withstand supply transients up to 30 V.

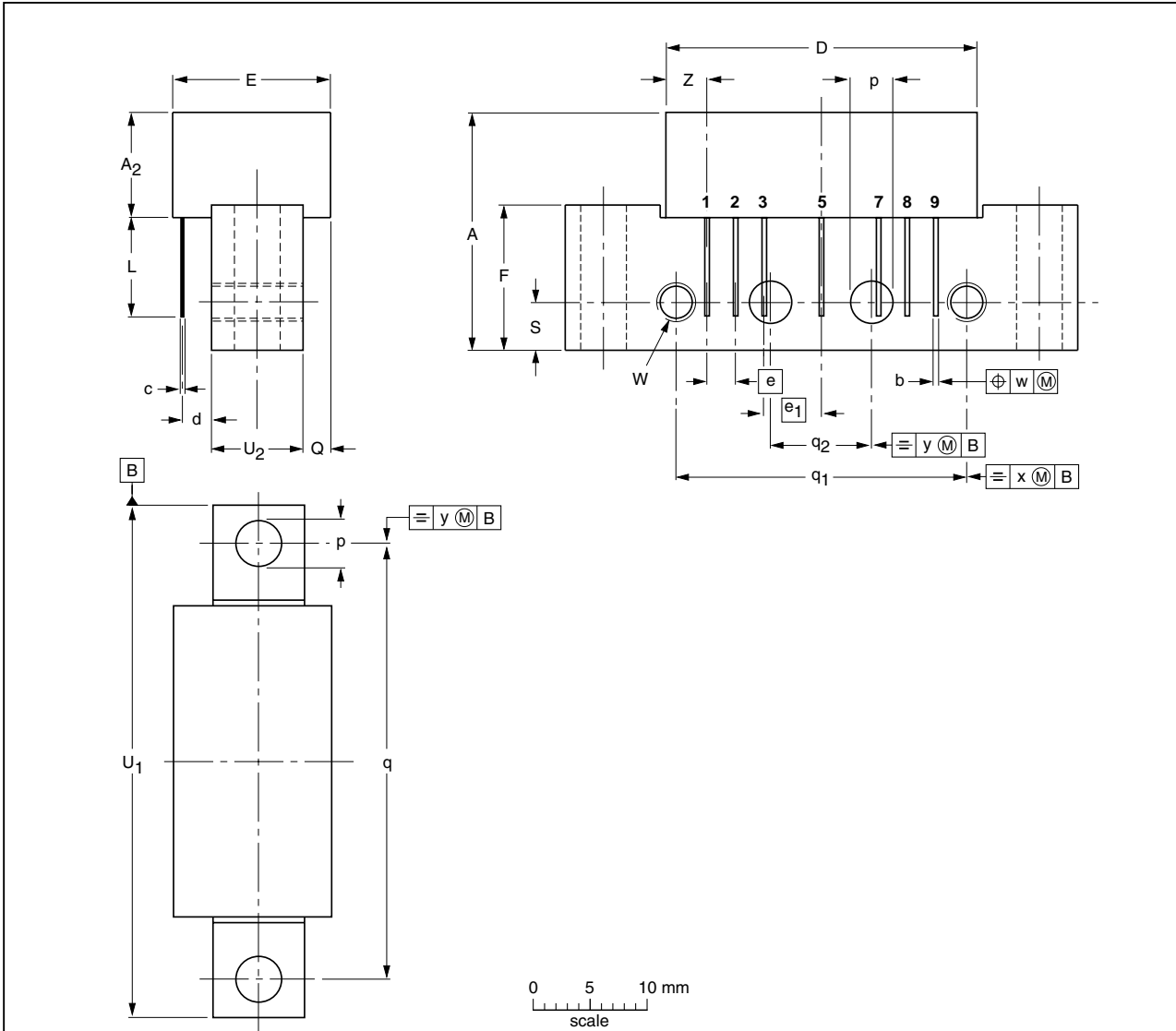
[4] $f_p = 55.25\text{ MHz}$; $V_p = 46\text{ dBmV}$; $f_q = 391.25\text{ MHz}$; $V_q = 46\text{ dBmV}$; measured at $f_p + f_q = 446.5\text{ MHz}$.

[5] Measured according to DIN45004B; $f_p = 440.25\text{ MHz}$; $V_p = V_o$; $f_q = 447.25\text{ MHz}$; $V_q = V_o - 6\text{ dB}$; $f_r = 449.25\text{ MHz}$; $V_r = V_o - 6\text{ dB}$; measured at $f_p + f_q - f_r = 438.25\text{ MHz}$.

6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads

SOT115J



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₂ max.	b	c	D max.	d	E max.	e	e ₁	F	L min.	p	Q max.	q	q ₁	q ₂	S	U ₁	U ₂	W	w	x	y	Z max.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.04 2.54	13.75	2.54	5.08	12.7	8.8	4.15 3.85	2.4	38.1	25.4	10.2	4.2	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	3.8

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115J						04-02-04- 10-06-18

Fig 1. Package outline SOT115J

7. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGY585A v.6	20100929	Product data sheet	-	BGY585A v.5
Modifications:		<ul style="list-style-type: none">• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.• Legal texts have been adapted to the new company name where appropriate.• Package outline drawings have been updated to the latest version.		
BGY585A v.5 (9397 750 14432)	20050124	Product data sheet	-	BGY585A v.4
BGY585A v.4 (9397 750 08802)	20011018	Product specification	-	BGY585A v.3
BGY585A v.3 (9397 750 06341)	19990326	Product specification	-	BGY585A v.2

8. Legal information

8.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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